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DATE: June 1, 2004
FILE NO: AMAT/5262/CMP/CMP/RKK
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PAGE(S) with cover: 2
ORIGINAL TO FOLLOW? ☐ YES ☒ NO

SECOND RESPONSE TO FINAL OFFICE ACTION DATED FEBRUARY 6, 2004

TITLE: Method and Apparatus For Forming Metal Layers
U.S. SERIAL NO.: 09/961,134
FILING DATE: September 21, 2001
INVENTOR: Tsai, et al.
EXAMINER: Edna Wong
GROUP ART UNIT: 1753
CONFIRMATION NO.: 4110

CONFIDENTIALITY NOTE

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IN THE CLAIMS:

The status of the claims is as follows:

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- 1-23. (Cancelled)
24. (Previously Presented): A method of forming a metal layer on a substrate, comprising:
- positioning a substrate in an electroplating cell having a porous pad and an electrolyte solution therein;
 - contacting at least a portion of the substrate to the porous pad;
 - forming a metal layer on the substrate by biasing the substrate relative to an electrode at a first electrical bias and then biasing the substrate relative to the electrode at a second electrical bias, wherein the first electrical bias deposits metal on the substrate and the second electrical bias removes metal from the substrate; and
 - varying the magnitude of the second electrical bias relative to the first electrical bias as the metal layer is formed.
25. (Cancelled)